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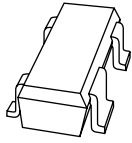
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BFG520W; BFG520W/X

NPN 9 GHz wideband transistors

Rev. 04 — 21 November 2007

Product data sheet

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NXP Semiconductors

NPN 9 GHz wideband transistors

BFG520W; BFG520W/X

FEATURES

- High power gain
- Low noise figure
- High transition frequency
- Gold metallization ensures excellent reliability.

APPLICATIONS

RF front end wideband applications in the GHz range, such as analog and digital cellular telephones, cordless telephones (CT2, CT3, PCN, DECT, etc.), radar detectors, pagers, satellite television tuners (SATV) and repeater amplifiers in fibre-optic systems.

DESCRIPTION

NPN silicon planar epitaxial transistor in a 4-pin dual-emitter SOT343N plastic package.

MARKING

TYPE NUMBER	CODE
BFG520W	N3
BFG520W/X	N4

PINNING

PIN	DESCRIPTION	
	BFG520W	BFG520W/X
1	collector	collector
2	base	emitter
3	emitter	base
4	emitter	emitter

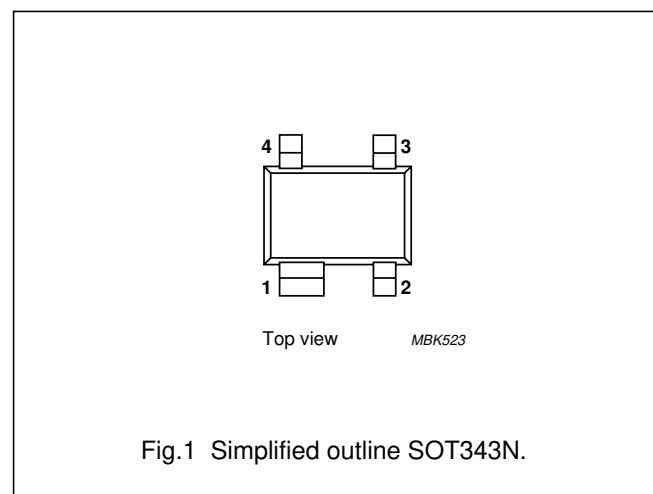


Fig.1 Simplified outline SOT343N.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	–	–	20	V
V_{CES}	collector-emitter voltage	$R_{BE} = 0$	–	–	15	V
I_C	collector current (DC)		–	–	70	mA
P_{tot}	total power dissipation	$T_s \leq 85\text{ }^\circ\text{C}$	–	–	500	mW
h_{FE}	DC current gain	$I_C = 20\text{ mA}; V_{CE} = 6\text{ V}$	60	120	250	
C_{re}	feedback capacitance	$I_C = 0; V_{CB} = 6\text{ V}; f = 1\text{ MHz}$	–	0.35	–	pF
f_T	transition frequency	$I_C = 20\text{ mA}; V_{CE} = 6\text{ V}; f = 1\text{ GHz}; T_{amb} = 25\text{ }^\circ\text{C}$	–	9	–	GHz
G_{UM}	maximum unilateral power gain	$I_C = 20\text{ mA}; V_{CE} = 6\text{ V}; f = 900\text{ MHz}; T_{amb} = 25\text{ }^\circ\text{C}$	–	17	–	dB
$ S_{21} ^2$	insertion power gain	$I_C = 20\text{ mA}; V_{CE} = 6\text{ V}; f = 900\text{ MHz}; T_{amb} = 25\text{ }^\circ\text{C}$	16	17	–	dB
F	noise figure	$\Gamma_s = \Gamma_{opt}; I_C = 5\text{ mA}; V_{CE} = 6\text{ V}; f = 900\text{ MHz}$	–	1.1	1.6	dB

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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter	–	20	V
V _{CES}	collector-emitter voltage	R _{BE} = 0	–	15	V
V _{EBO}	emitter-base voltage	open collector	–	2.5	V
I _C	collector current (DC)		–	70	mA
P _{tot}	total power dissipation	T _s ≤ 85 °C; see Fig.2; note 1	–	500	mW
T _{stg}	storage temperature		–65	+150	°C
T _j	junction temperature		–	175	°C

Note

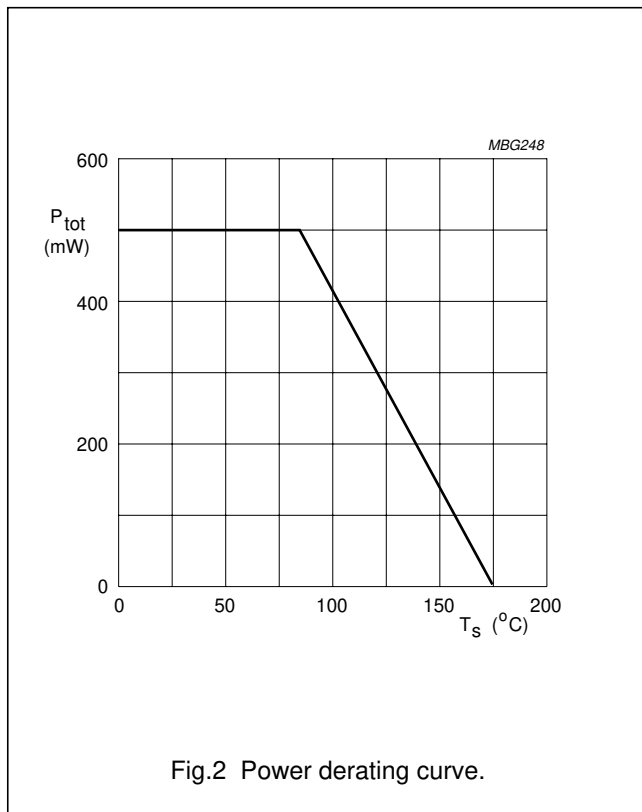
1. T_s is the temperature at the soldering point of the collector pin.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-s}	thermal resistance from junction to soldering point	T _s ≤ 85 °C; note 1	180	K/W

Note

1. T_s is the temperature at the soldering point of the collector pin.



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CHARACTERISTICS

$T_j = 25\text{ °C}$ unless otherwise specified.

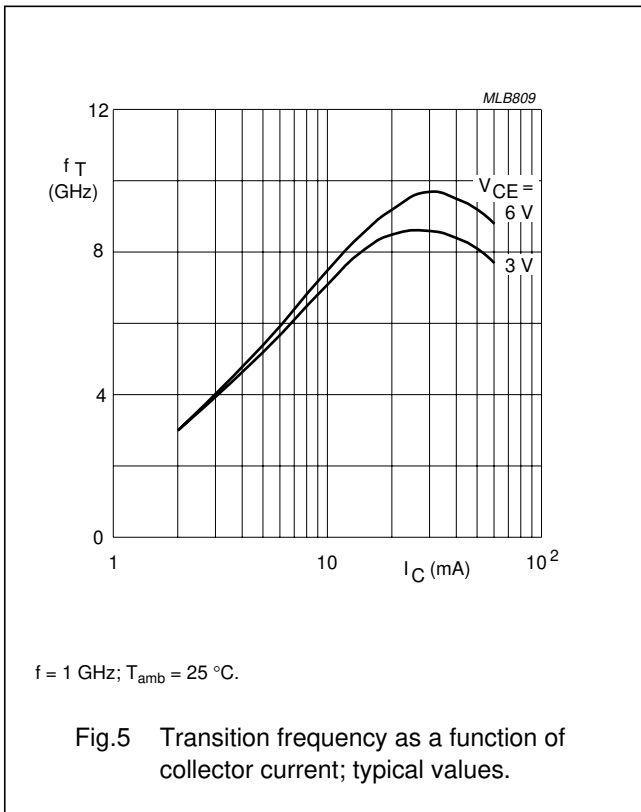
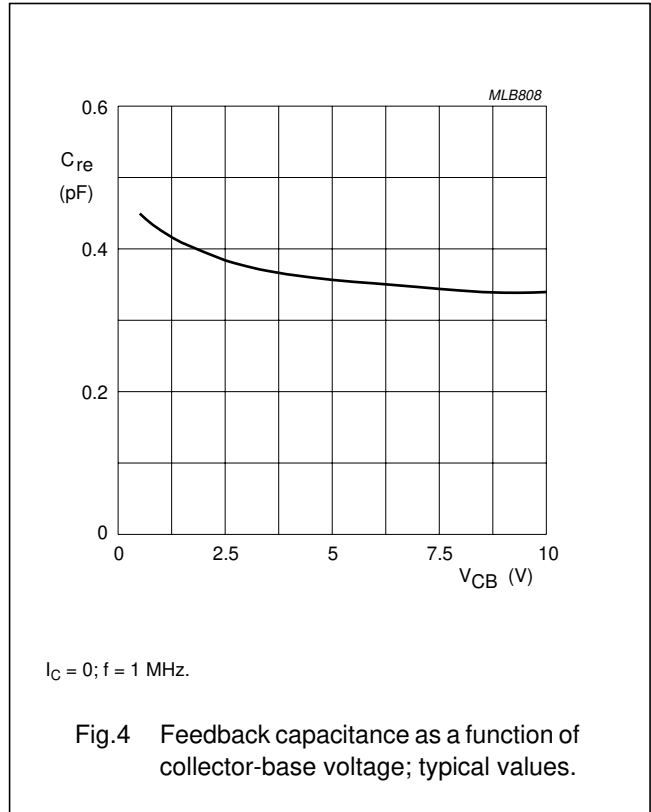
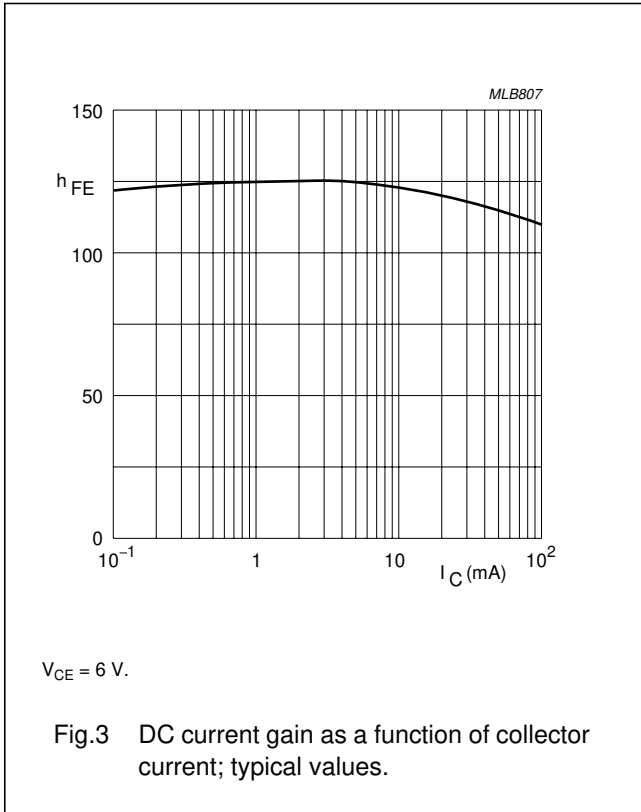
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{(BR)CBO}$	collector-base breakdown voltage	$I_C = 10\ \mu\text{A}; I_E = 0$	20	–	–	V
$V_{(BR)CES}$	collector-emitter breakdown voltage	$I_C = 10\ \mu\text{A}; R_{BE} = 0$	15	–	–	V
$V_{(BR)EBO}$	emitter-base breakdown voltage	$I_E = 10\ \mu\text{A}; I_C = 0$	2.5	–	–	V
I_{CBO}	collector leakage current	$V_{CB} = 6\ \text{V}; I_E = 0$	–	–	50	nA
h_{FE}	DC current gain	$I_C = 20\ \text{mA}; V_{CE} = 6\ \text{V};$ see Fig.3	60	120	250	
C_{re}	feedback capacitance	$I_C = 0; V_{CB} = 6\ \text{V}; f = 1\ \text{MHz};$ see Fig.4	–	0.35	–	pF
f_T	transition frequency	$I_C = 20\ \text{mA}; V_{CE} = 6\ \text{V}; f = 1\ \text{GHz};$ $T_{amb} = 25\text{ °C};$ see Fig.5	–	9	–	GHz
G_{UM}	maximum unilateral power gain; note 1	$I_C = 20\ \text{mA}; V_{CE} = 6\ \text{V}; f = 900\ \text{MHz};$ $T_{amb} = 25\text{ °C}$	–	17	–	dB
		$I_C = 20\ \text{mA}; V_{CE} = 6\ \text{V}; f = 2\ \text{GHz};$ $T_{amb} = 25\text{ °C}$	–	11	–	dB
$ S_{21} ^2$	insertion power gain	$I_C = 20\ \text{mA}; V_{CE} = 6\ \text{V}; f = 900\ \text{MHz};$ $T_{amb} = 25\text{ °C}$	16	17	–	dB
F	noise figure	$\Gamma_s = \Gamma_{opt}; I_C = 5\ \text{mA}; V_{CE} = 6\ \text{V};$ $f = 900\ \text{MHz}$	–	1.1	1.6	dB
		$\Gamma_s = \Gamma_{opt}; I_C = 20\ \text{mA}; V_{CE} = 6\ \text{V};$ $f = 900\ \text{MHz}$	–	1.6	2.1	dB
		$\Gamma_s = \Gamma_{opt}; I_C = 5\ \text{mA}; V_{CE} = 6\ \text{V};$ $f = 2\ \text{GHz}$	–	1.85	–	dB
PL_1	output power at 1 dB gain compression	$I_C = 20\ \text{mA}; V_{CE} = 6\ \text{V}; f = 900\ \text{MHz};$ $R_L = 50\ \Omega; T_{amb} = 25\text{ °C}$	–	17	–	dBm
ITO	third order intercept point	note 2	–	26	–	dBm
V_o	output voltage	note 3	–	275	–	mV
d_2	second order intermodulation distortion	note 4	–	–50	–	dB

Notes

- G_{UM} is the maximum unilateral power gain, assuming S_{12} is zero. $G_{UM} = 10 \log \frac{|S_{21}|^2}{(1 - |S_{11}|^2)(1 - |S_{22}|^2)}$ dB.
- $I_C = 20\ \text{mA}; V_{CE} = 6\ \text{V}; R_L = 50\ \Omega; T_{amb} = 25\text{ °C};$
 $f_p = 900\ \text{MHz}; f_q = 902\ \text{MHz};$ measured at $2f_p - f_q = 898\ \text{MHz}$ and $2f_q - f_p = 904\ \text{MHz}.$
- $d_{im} = -60\ \text{dB}$ (DIN45004B); $I_C = 20\ \text{mA}; V_{CE} = 6\ \text{V}; V_p = V_o; V_q = V_o - 6\ \text{dB}; V_r = V_o - 6\ \text{dB}; R_L = 75\ \Omega;$
 $f_p = 795.25\ \text{MHz}; f_q = 803.25\ \text{MHz}; f_r = 805.25\ \text{MHz};$ measured at $f_p + f_q - f_r = 793.25\ \text{MHz}.$
- $I_C = 20\ \text{mA}; V_{CE} = 6\ \text{V}; V_o = 75\ \text{mV}; R_L = 75\ \Omega; T_{amb} = 25\text{ °C};$
 $f_p = 250\ \text{MHz}; f_q = 560\ \text{MHz};$ measured at $f_p + f_q = 810\ \text{MHz}.$

NPN 9 GHz wideband transistors

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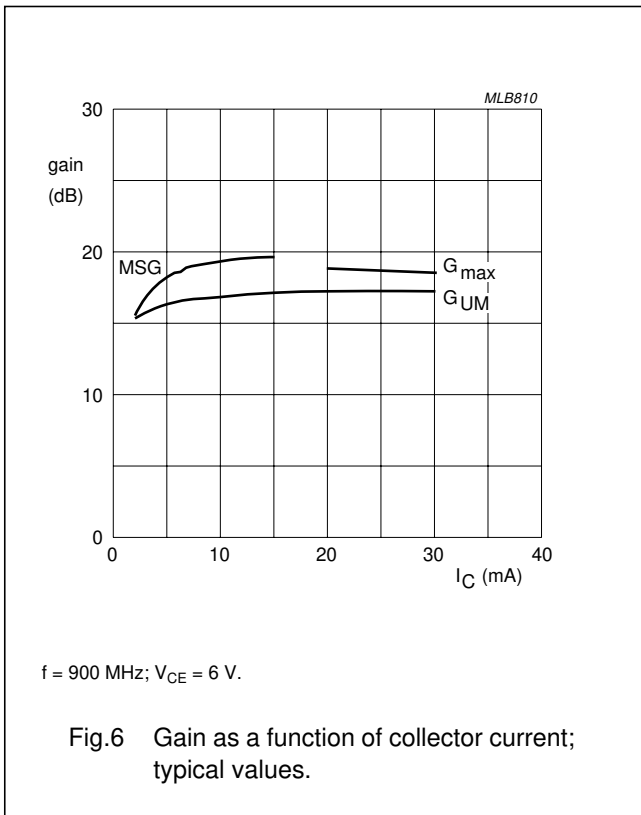


Fig.6 Gain as a function of collector current; typical values.

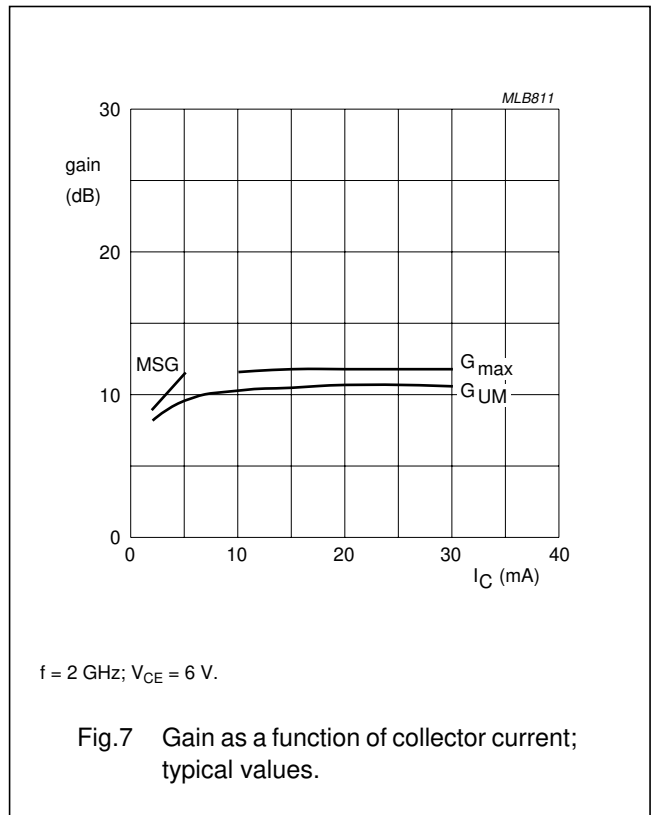


Fig.7 Gain as a function of collector current; typical values.

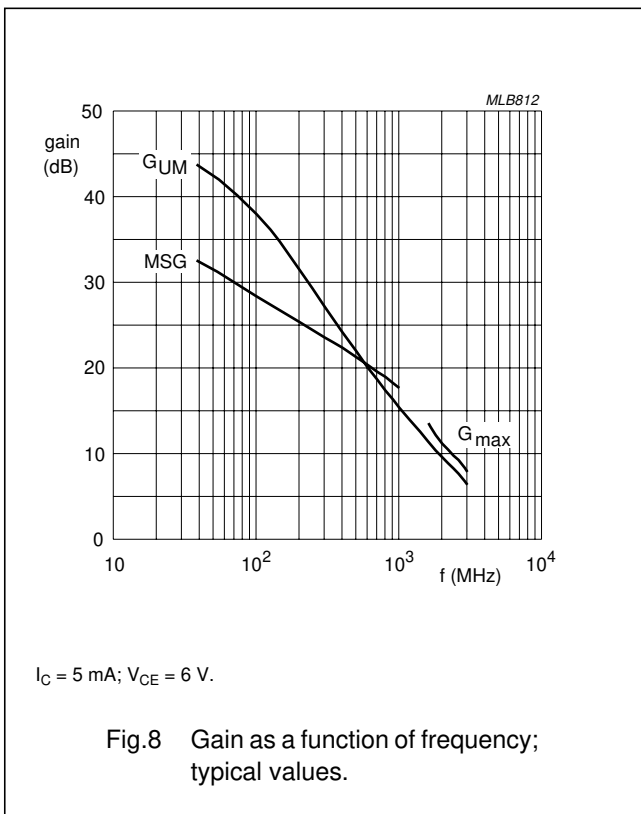


Fig.8 Gain as a function of frequency; typical values.

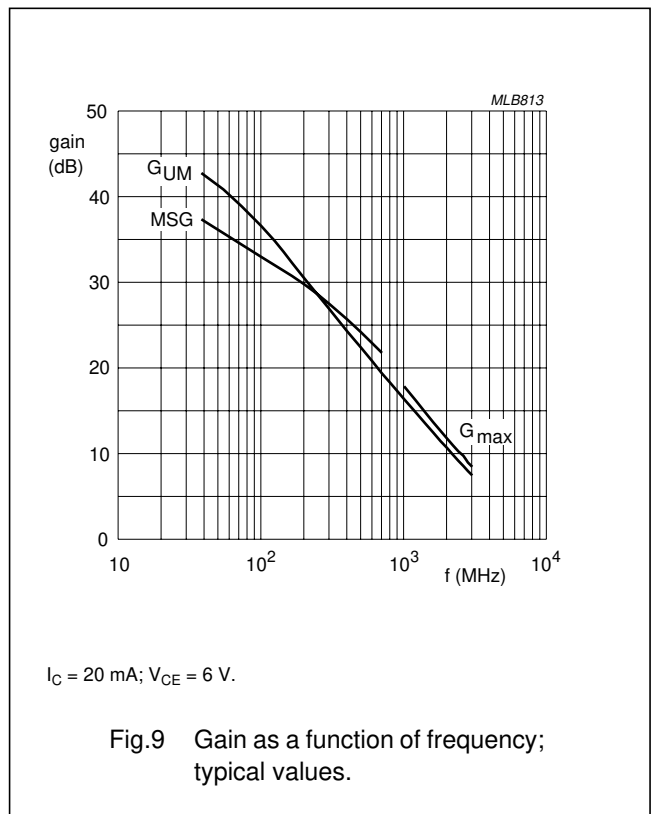
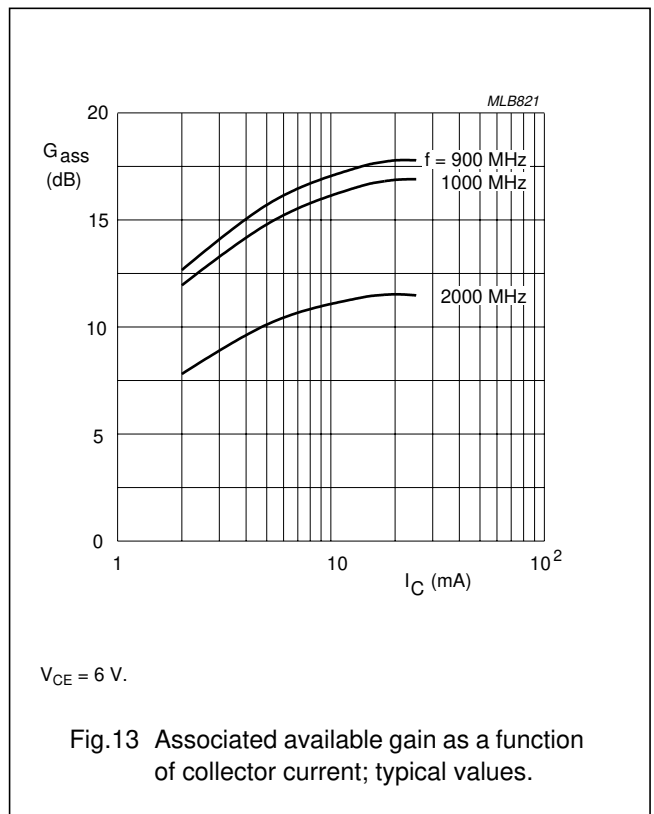
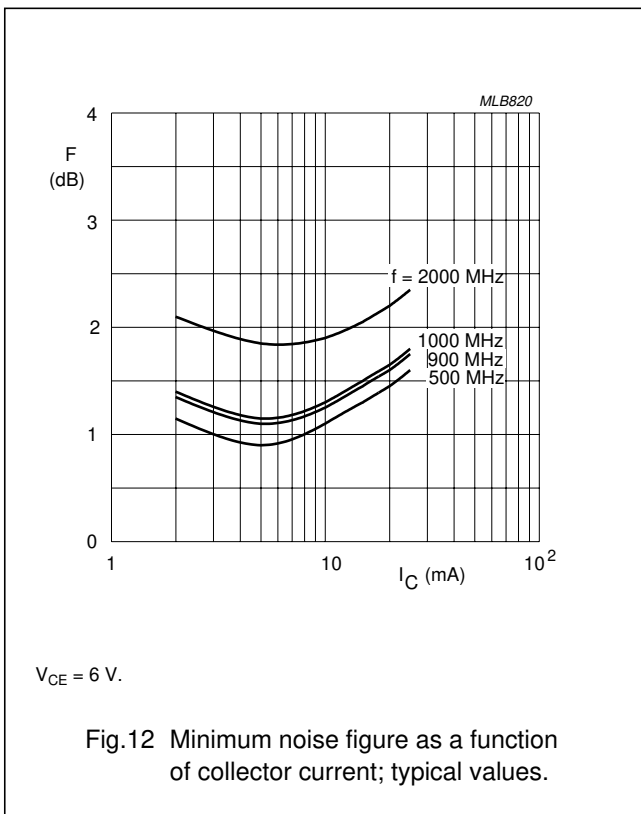
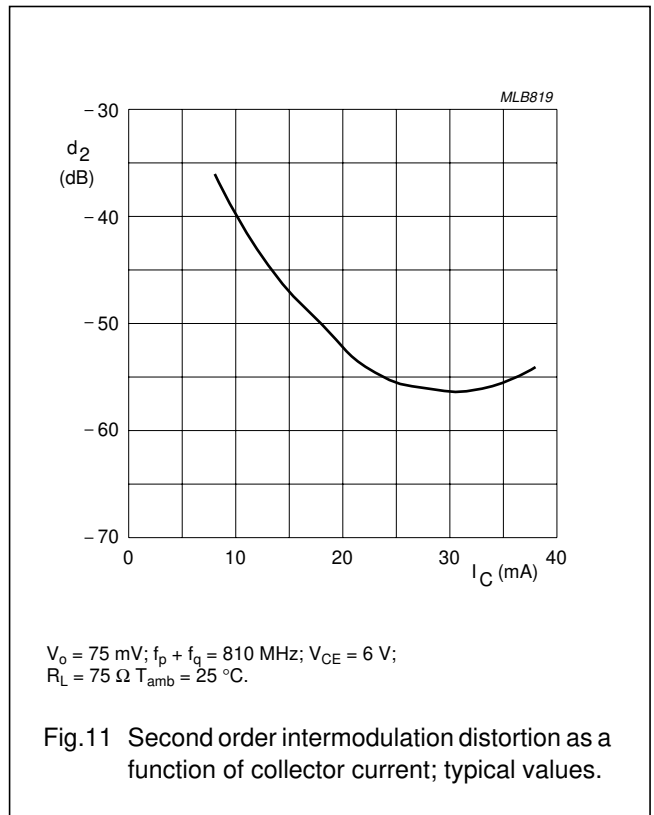
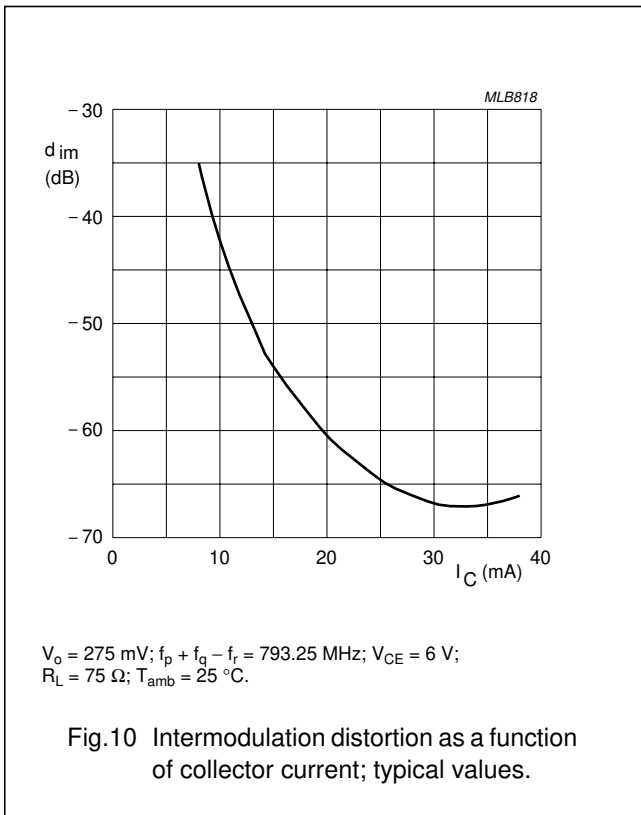


Fig.9 Gain as a function of frequency; typical values.

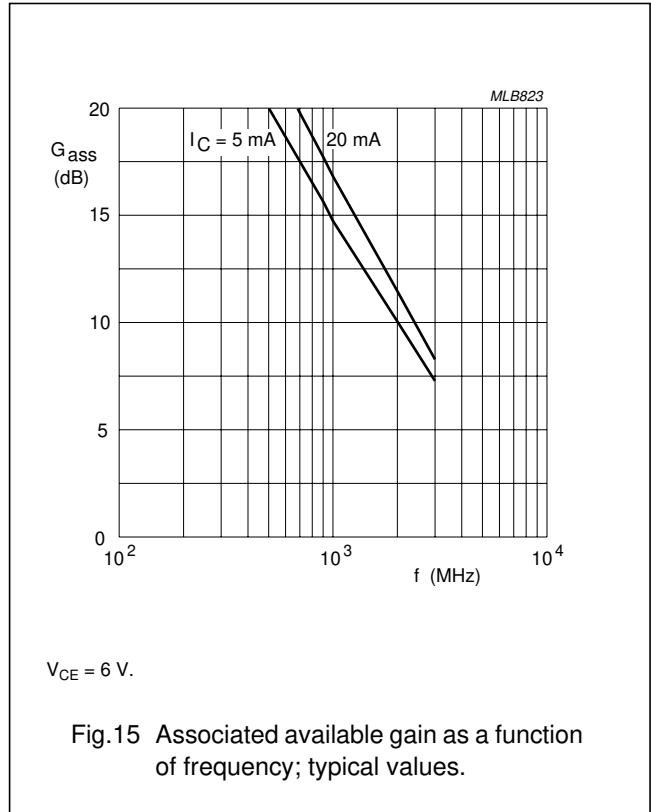
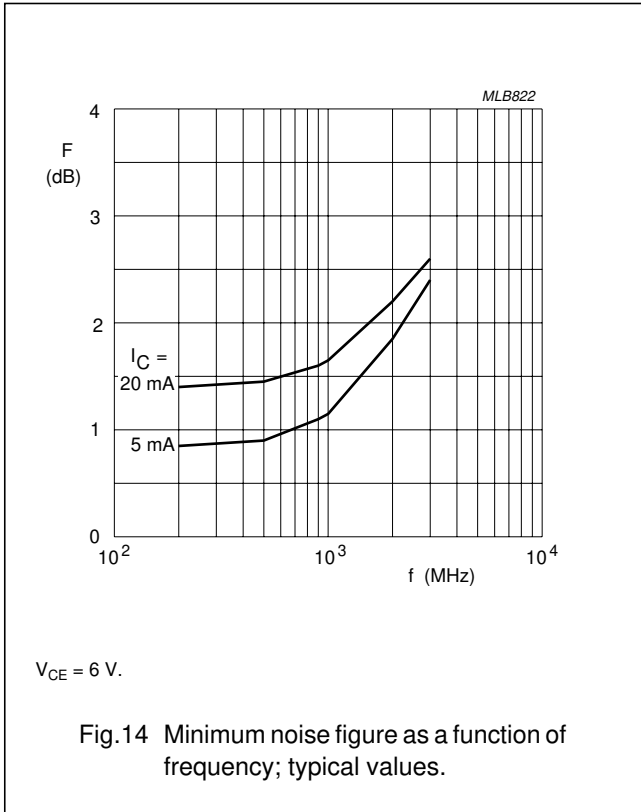
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BFG520W; BFG520W/X



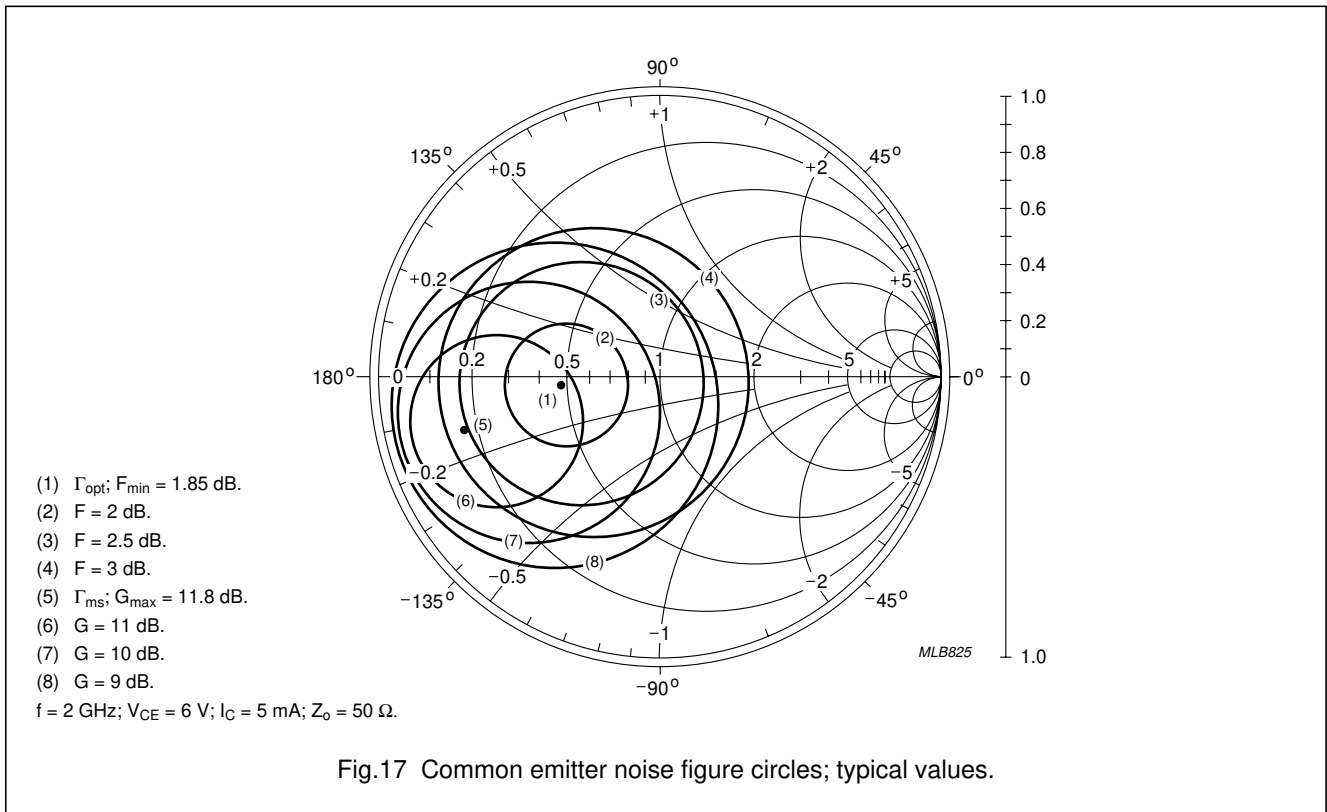
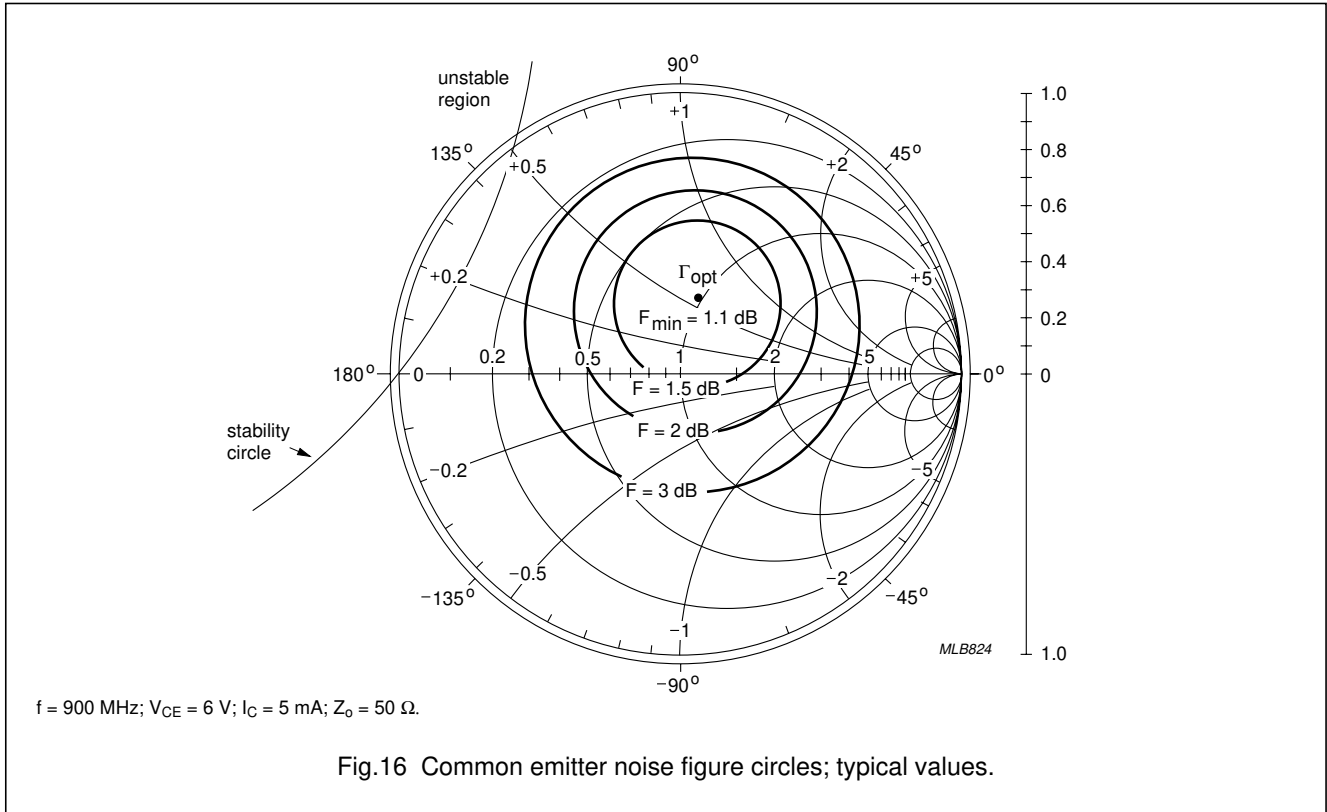
NPN 9 GHz wideband transistors

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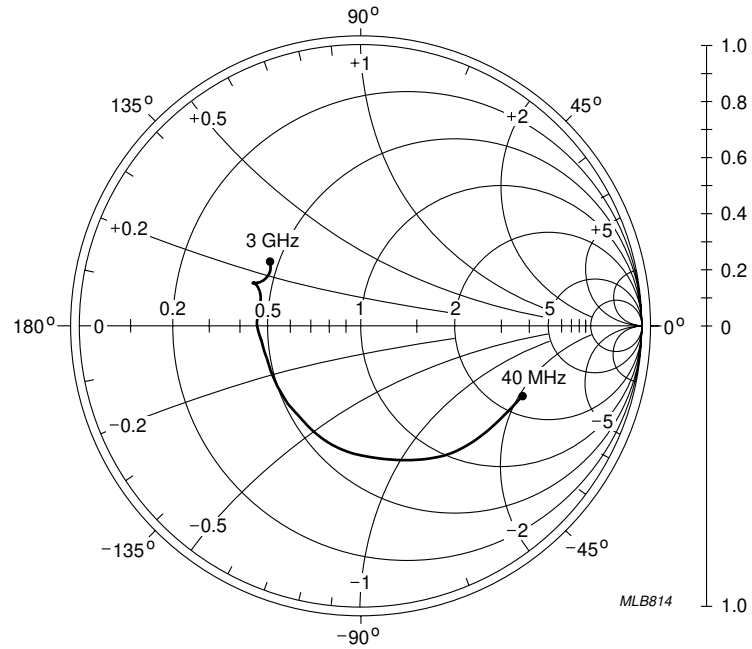
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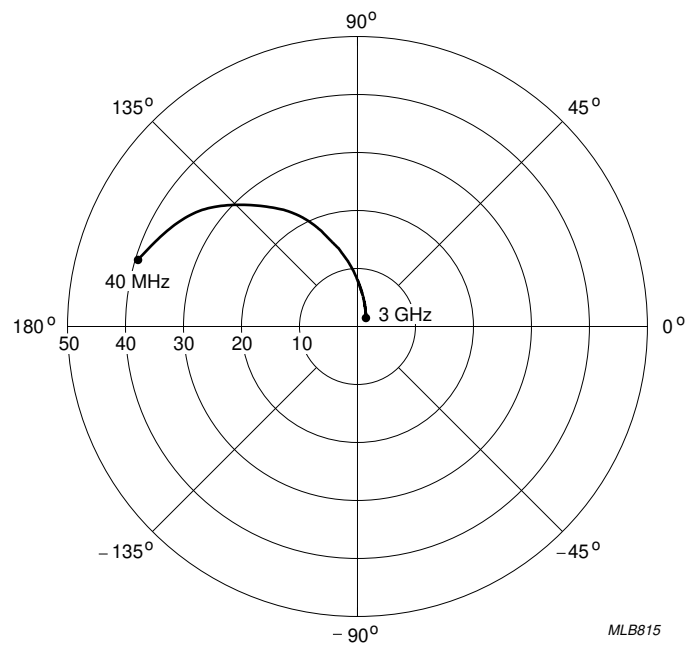
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$V_{CE} = 6\text{ V}; I_C = 20\text{ mA}; Z_0 = 50\ \Omega.$

Fig.18 Common emitter input reflection coefficient (S_{11}); typical values.

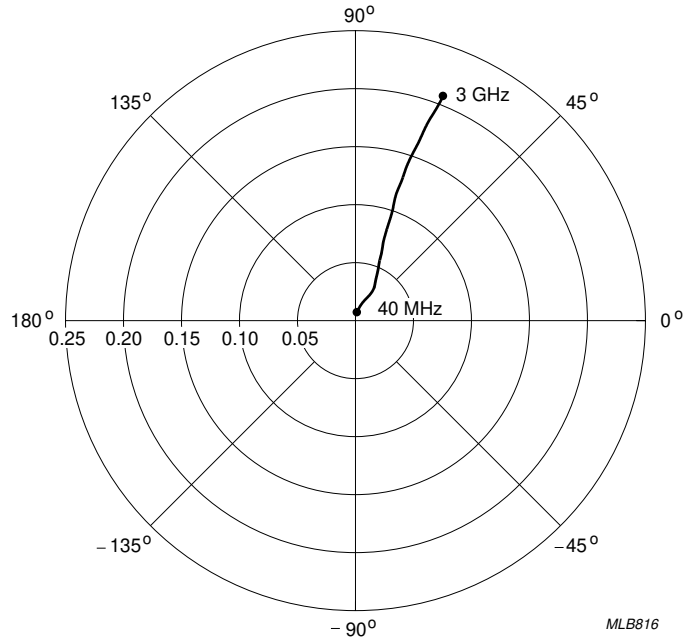


$V_{CE} = 6\text{ V}; I_C = 20\text{ mA}.$

Fig.19 Common emitter forward transmission coefficient (S_{21}); typical values.

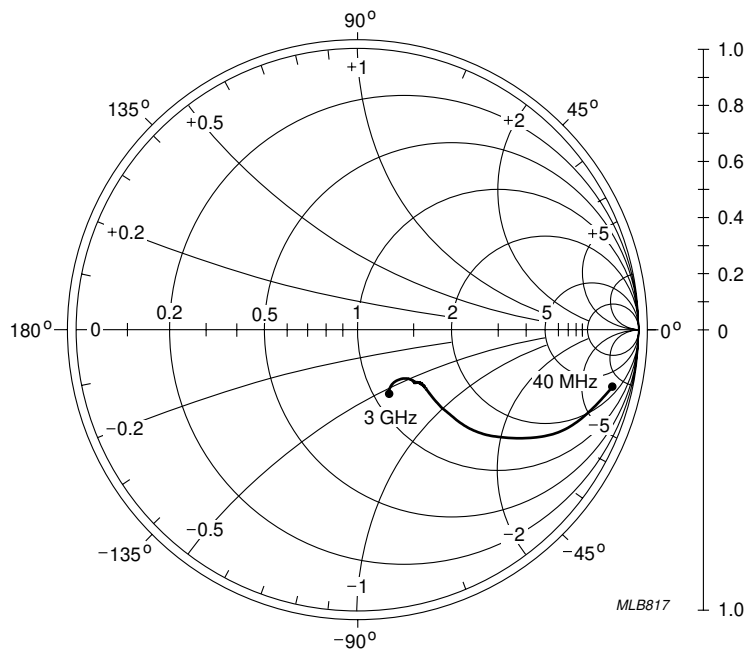
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$V_{CE} = 6\text{ V}; I_C = 20\text{ mA}$.

Fig.20 Common emitter reverse transmission coefficient (S_{12}); typical values.



$V_{CE} = 6\text{ V}; I_C = 20\text{ mA}; Z_0 = 50\ \Omega$.

Fig.21 Common emitter output reflection coefficient (S_{22}); typical values.

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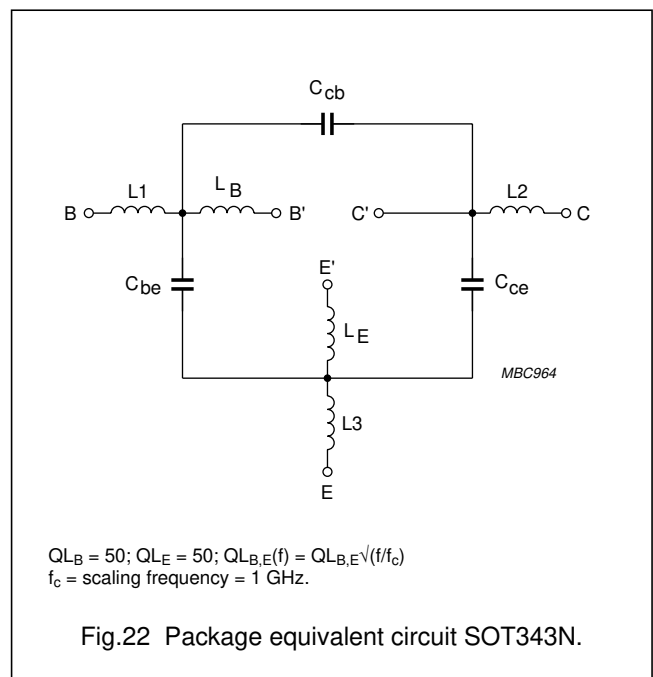
SPICE parameters for the BFG520W die

SEQUENCE No.	PARAMETER	VALUE	UNIT
1	IS	1.016	fA
2	BF	220.1	–
3	NF	1.000	–
4	VAF	48.06	V
5	IKF	510	mA
6	ISE	283	fA
7	NE	2.035	–
8	BR	100.7	–
9	NR	0.988	–
10	VAR	1.692	V
11	IKR	2.352	mA
12	ISC	24.48	aA
13	NC	1.022	–
14	RB	10.00	Ω
15	IRB	1.000	μA
16	RBM	10.00	Ω
17	RE	775.3	mΩ
18	RC	2.210	Ω
19 (1)	XTB	0.000	–
20 (1)	EG	1.110	eV
21 (1)	XTI	3.000	–
22	CJE	1.245	pF
23	VJE	600.0	mV
24	MJE	0.258	–
25	TF	8.616	ps
26	XTF	6.788	–
27	VTF	1.414	V
28	ITF	110.3	mA
29	PTF	45.01	deg
30	CJC	447.6	fF
31	VJC	189.2	mV
32	MJC	0.070	–
33	XCJC	0.130	–
34	TR	543.7	ps
35 (1)	CJS	0.000	F

SEQUENCE No.	PARAMETER	VALUE	UNIT
36 (1)	VJS	750.0	mV
37 (1)	MJS	0.000	–
38	FC	0.780	–

Note

1. These parameters have not been extracted, the default values are shown.



List of components (see Fig.22)

DESIGNATION	VALUE	UNIT
C _{be}	70	fF
C _{cb}	50	fF
C _{ce}	115	fF
L1	0.34	nH
L2	0.10	nH
L3	0.25	nH
L _B	0.40	nH
L _E	0.40	nH

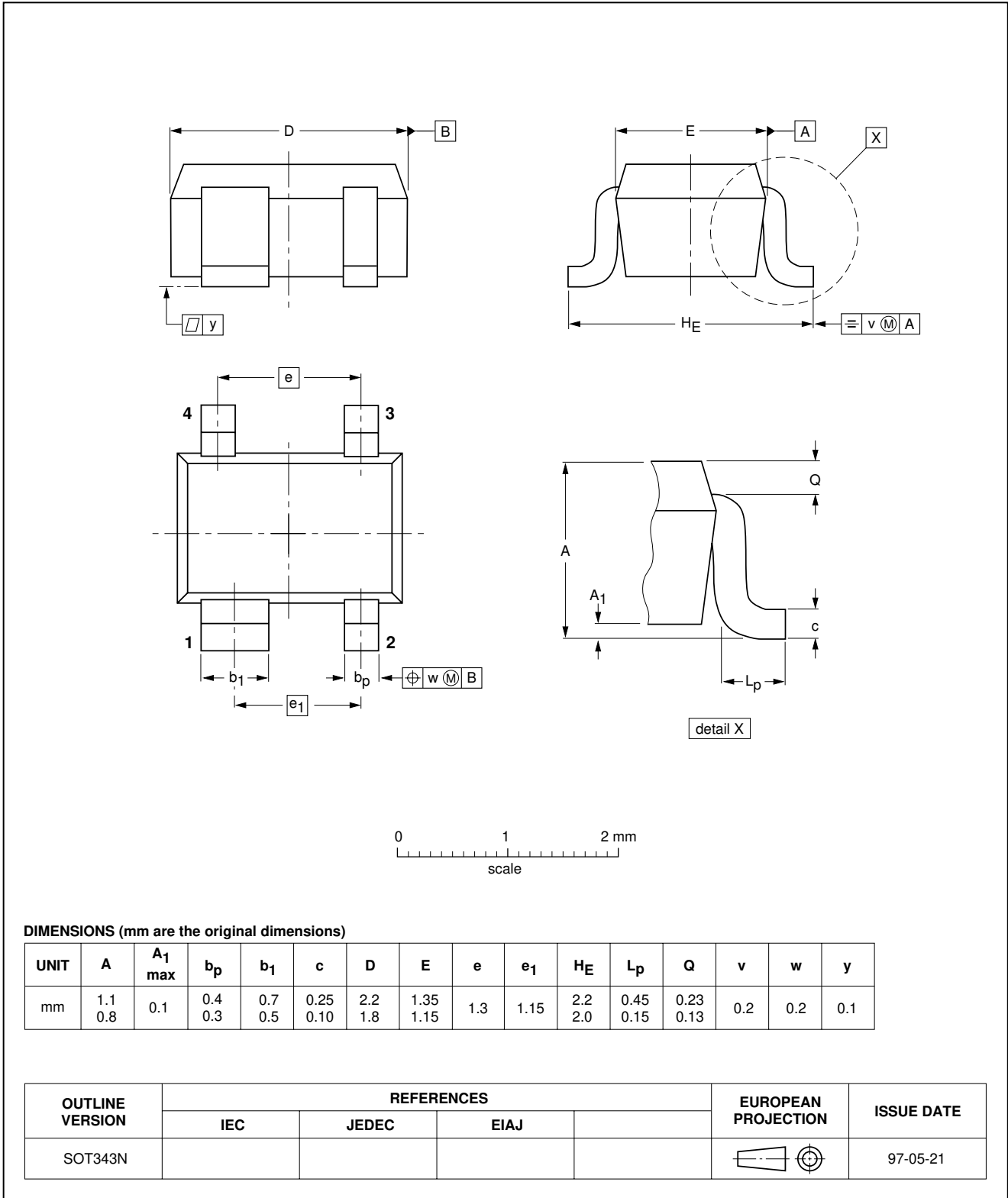
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PACKAGE OUTLINE

Plastic surface mounted package; 4 leads

SOT343N



Legal information

Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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[2] The term 'short data sheet' is explained in section "Definitions".

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Revision history

Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BFG520W_N_4	20071121	Product data sheet	-	BFG520W_X_3
Modifications:	<ul style="list-style-type: none"> Page 2; text in Pinning table changed 			
BFG520W_X_3	19981002	Product specification	-	BFG520W_2
BFG520W_2	19950824	Product specification	-	BFG520W_1
BFG520W_1	19940829	-	-	-

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Date of release: 21 November 2007

Document identifier: BFG520W_X_N_4